

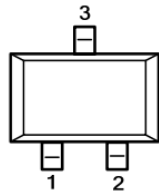
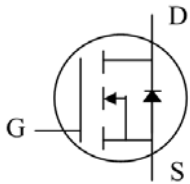
**N-Channel 50V MOSFET**

**Features:**

- Surface-mounted package
- High Density Cell Design
- Low Threshold Voltage
- Halogen free

**Application**

- DC-DC
- Portable appliance
- Power management



**Top View  
SOT23S-3L**

$B_{VDSS} = 50V$  ,  
 $R_{DS(ON)} < 10\Omega @ V_{GS} = 2.75V$   
 $R_{DS(ON)} < 3.5\Omega @ V_{GS} = 5.0V$   
 $I_D = 200mA$

**Absolute Maximum Ratings (T<sub>A</sub>=25°C Unless Otherwise Noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DSS</sub>	50	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	200	mA
Ta=25°C			
Pulsed Drain Current(t <sub>p</sub> ≤ 10us)	I <sub>DM</sub>	800	mA
Power Dissipation	P <sub>D</sub>	225	mW
Ta=25°C			
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C

**Thermal Characteristics**

Symbol	Characteristic	Max.	Units
R <sub>θJA</sub>	Junction-to-Ambient	556	°C/W

**N-Channel 50V MOSFET**

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static <sup>(1)</sup>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	50	--	--	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=1mA$	0.5	--	1.5	V
$I_{GSS}$	Gate-Body Leakage	$V_{DS}=0V, V_{GS}=\pm 20V$	--	--	$\pm 0.1$	$\mu A$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=25V, V_{GS}=0V$	--	--	0.1	$\mu A$
		$V_{DS}=50V, V_{GS}=0V$	--	--	0.5	
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=2.75V, I_D=200mA$	--	--	10	$\Omega$
		$V_{GS}=5.0V, I_D=200mA$	--	--	3.5	$\Omega$
$g_{FS}$	Forward Transconductance	$I_D=200mA, V_{DS}=25V$	100	--	--	mmhos
Dynamic <sup>(2)</sup>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1.0MHz$	--	40	50	$\mu F$
$C_{oss}$	Output Capacitance		--	12	25	
$C_{rss}$	Reverse Transfer Capacitance		--	3.5	5.0	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=30V, I_D=0.2A$	--	--	20	ns
$t_{d(off)}$	Turn-Off Delay Time		--	--	20	

Note :

- (1) Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- (2) Switching characteristics are independent of operating junction temperature.

N-Channel 50V MOSFET

TYPICAL ELECTRICAL CHARACTERISTICS

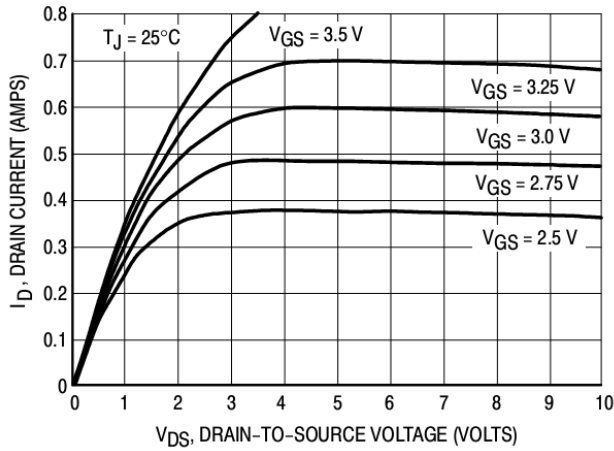


Figure 1. On-Region Characteristics

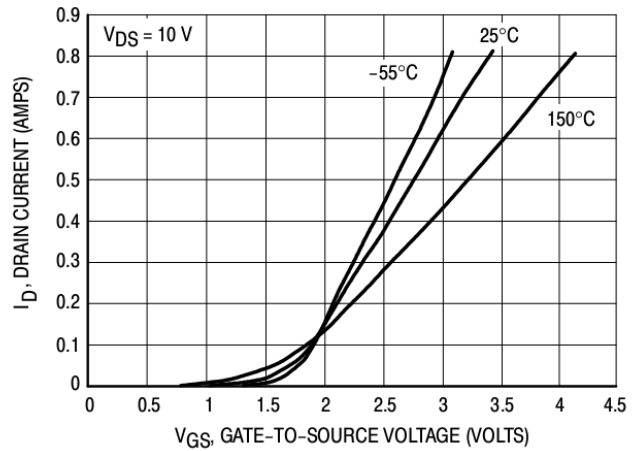


Figure 2. Transfer Characteristics

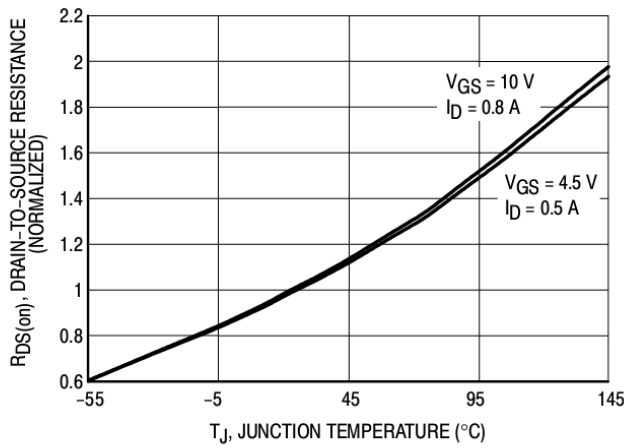


Figure 3. On-Resistance Variation with Temperature

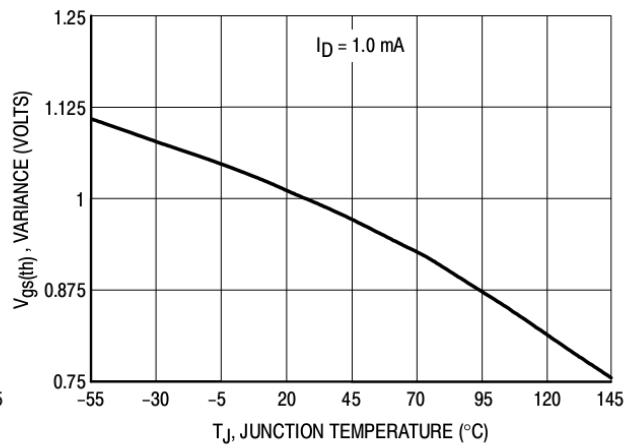


Figure 4. Threshold Voltage Variation with Temperature

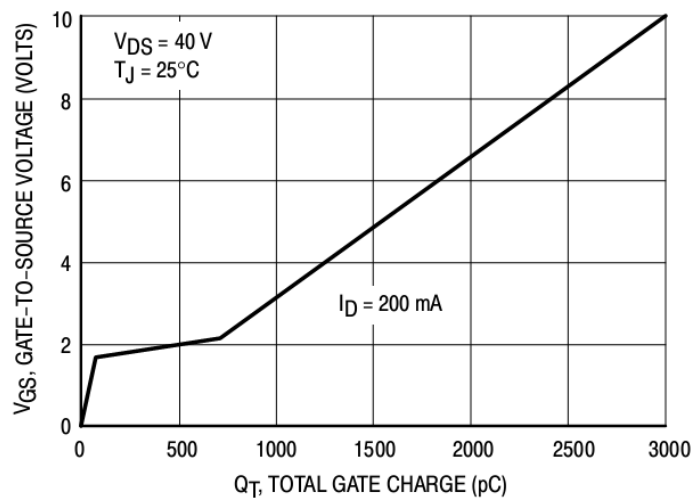


Figure 5. Gate Charge

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TYPICAL ELECTRICAL CHARACTERISTICS

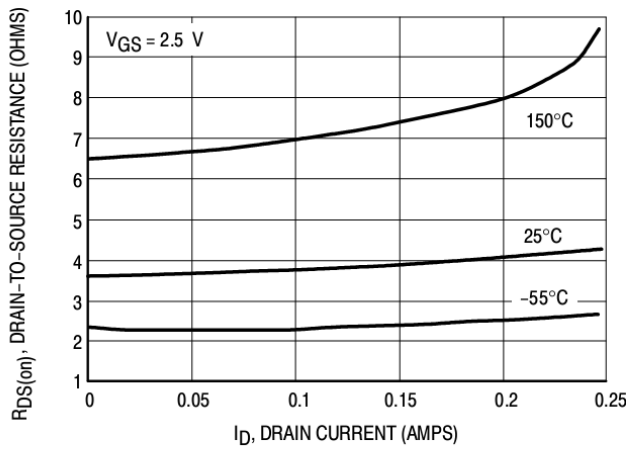


Figure 6. On-Resistance versus Drain Current

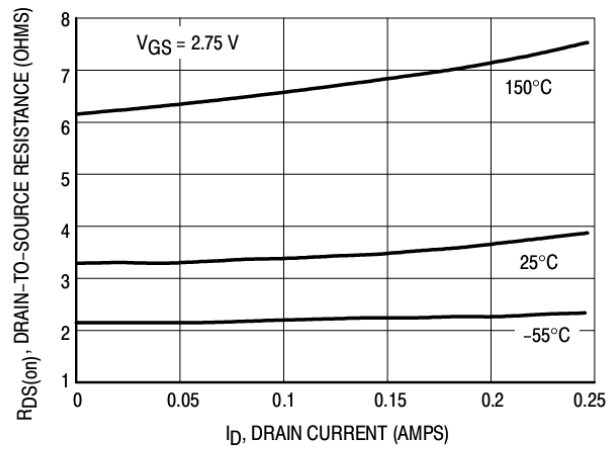


Figure 7. On-Resistance versus Drain Current

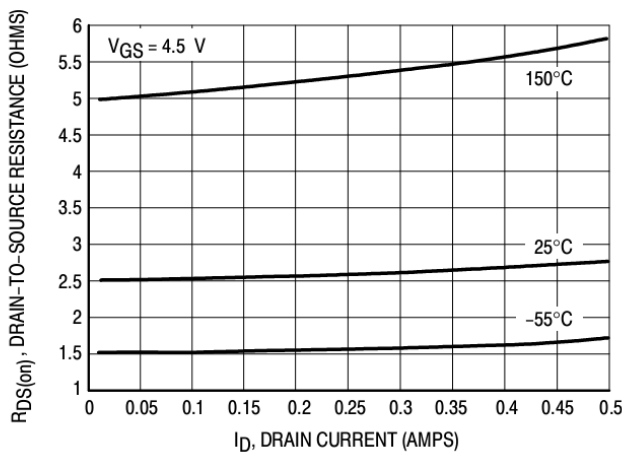


Figure 8. On-Resistance versus Drain Current

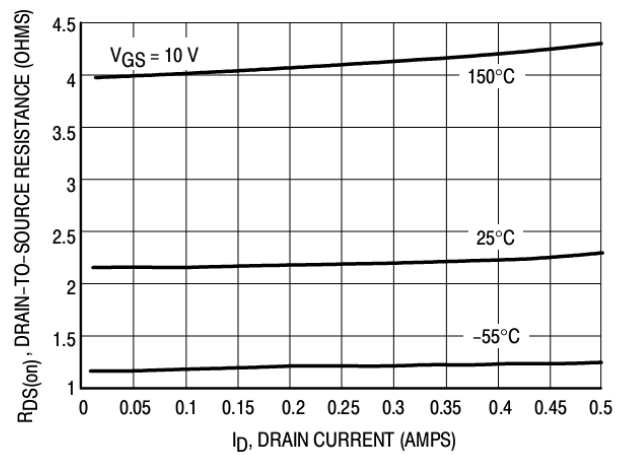


Figure 9. On-Resistance versus Drain Current

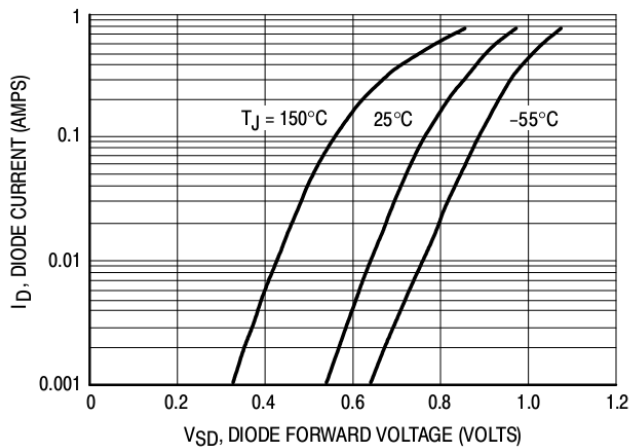


Figure 10. Body Diode Forward Voltage

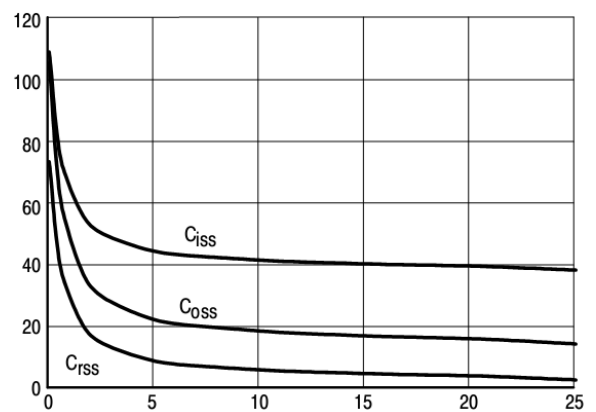
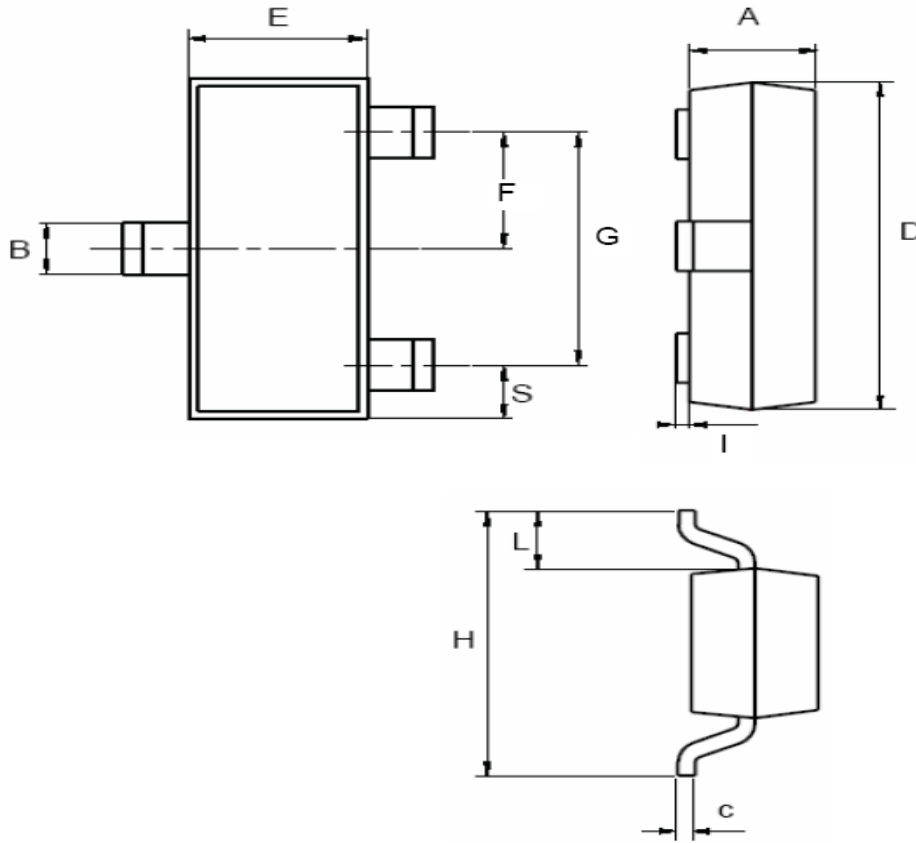


Figure 11. Capacitance

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SOT-23		
DIM.	MIN.	MAX.
A	0.89	1.40
B	0.30	0.51
C	0.085	0.18
D	2.75	3.04
E	1.20	1.60
F	0.85	1.05
G	1.70	2.10
H	2.10	2.75
I	0.0	0.1
L	0.60 typ.	
S	0.35	0.65
All Dimensions in millimeter		

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